

ABSTRACT

Integrated circuit device, electronic unit for smart
cards using said device and method of manufacturing said
device

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This invention relates to an integrated
circuit device, in particular for manufacturing smart
card electronic units for smart cards. It comprises:

10 an active layer (32) including a
semiconductor material within which integrated circuits
are formed and having a face (34) provided with a
plurality of electrical connection terminals (36) and a
second face, wherein said face has a thickness smaller
15 than 100 μm , and

a complementary layer (40) having a first
face (42) attached to the active face of the active
layer, a second face (44) and a side surface (48),
wherein said complementary layer includes a plurality of
20 recesses (46), each recess extending through the whole
thickness of the complementary layer, and extending from
a contact terminal (36) to said side surface (48).

25 Figure 2A